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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	1.65V ~ 1.95V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	-
Number of I/O	92
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	128-LQFP
Supplier Device Package	128-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4128c-5tn128c

Table 10. ORP Combinations for I/O Blocks with 12 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M1, M2, M3, M4, M5, M6, M7, M8
I/O 2	M2, M3, M4, M5, M6, M7, M8, M9
I/O 3	M4, M5, M6, M7, M8, M9, M10, M11
I/O 4	M5, M6, M7, M8, M9, M10, M11, M12
I/O 5	M6, M7, M8, M9, M10, M11, M12, M13
I/O 6	M8, M9, M10, M11, M12, M13, M14, M15
I/O 7	M9, M10, M11, M12, M13, M14, M15, M0
I/O 8	M10, M11, M12, M13, M14, M15, M0, M1
I/O 9	M12, M13, M14, M15, M0, M1, M2, M3
I/O 10	M13, M14, M15, M0, M1, M2, M3, M4
I/O 11	M14, M15, M0, M1, M2, M3, M4, M5

ORP Bypass and Fast Output Multiplexers

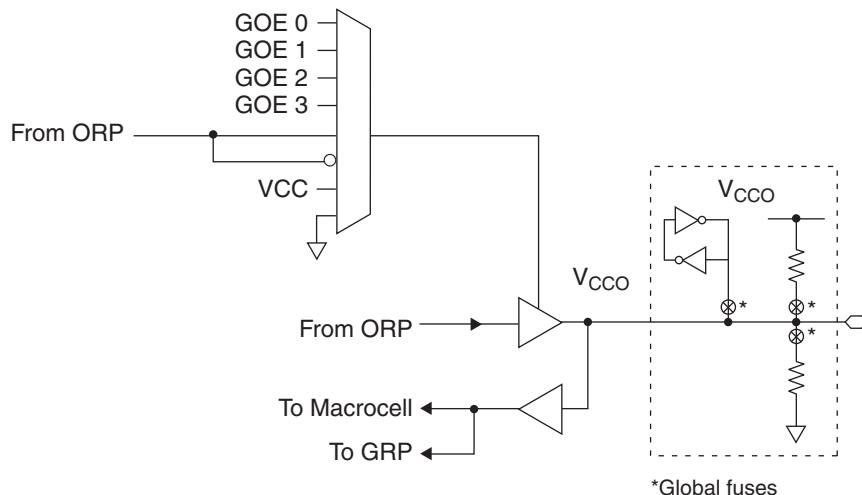
The ORP bypass and fast-path output multiplexer is a 4:1 multiplexer and allows the 5-PT fast path to bypass the ORP and be connected directly to the pin with either the regular output or the inverted output. This multiplexer also allows the register output to bypass the ORP to achieve faster t_{CO} .

Output Enable Routing Multiplexers

The OE Routing Pool provides the corresponding local output enable (OE) product term to the I/O cell.

I/O Cell

The I/O cell contains the following programmable elements: output buffer, input buffer, OE multiplexer and bus maintenance circuitry. Figure 8 details the I/O cell.

Figure 8. I/O Cell

Each output supports a variety of output standards dependent on the V_{CCO} supplied to its I/O bank. Outputs can also be configured for open drain operation. Each input can be programmed to support a variety of standards, independent of the V_{CCO} supplied to its I/O bank. The I/O standards supported are:

Absolute Maximum Ratings^{1, 2, 3}

	ispMACH 4000C/Z (1.8V)	ispMACH 4000B (2.5V)	ispMACH 4000V (3.3V)
Supply Voltage (V_{CC})	-0.5 to 2.5V	-0.5 to 5.5V	-0.5 to 5.5V
Output Supply Voltage (V_{CCO})	-0.5 to 4.5V	-0.5 to 4.5V	-0.5 to 4.5V
Input or I/O Tristate Voltage Applied ^{4, 5}	-0.5 to 5.5V	-0.5 to 5.5V	-0.5 to 5.5V
Storage Temperature	-65 to 150°C	-65 to 150°C	-65 to 150°C
Junction Temperature (T_j) with Power Applied	-55 to 150°C	-55 to 150°C	-55 to 150°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with Lattice [Thermal Management](#) document is required.
3. All voltages referenced to GND.
4. Undershoot of -2V and overshoot of (V_{IH} (MAX) + 2V), up to a total pin voltage of 6.0V, is permitted for a duration of < 20ns.
5. Maximum of 64 I/Os per device with $V_{IN} > 3.6V$ is allowed.

Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
V_{CC}	ispMACH 4000C	1.65	1.95	V
	ispMACH 4000Z	1.7	1.9	V
	ispMACH 4000Z, Extended Functional Voltage Operation	1.6 ^{1, 2}	1.9	V
	Supply Voltage for 2.5V Devices	2.3	2.7	V
T_j	Supply Voltage for 3.3V Devices	3.0	3.6	V
	Junction Temperature (Commercial)	0	90	C
	Junction Temperature (Industrial)	-40	105	C
	Junction Temperature (Extended)	-40	130	C

1. Devices operating at 1.6V can expect performance degradation up to 35%.
2. Applicable for devices with 2004 date codes and later. Contact factory for ordering instructions.

Erase Reprogram Specifications

Parameter	Min.	Max.	Units
Erase/Reprogram Cycle	1,000	—	Cycles

Note: Valid over commercial temperature range.

Hot Socketing Characteristics^{1, 2, 3}

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{DK}	Input or I/O Leakage Current	$0 \leq V_{IN} \leq 3.0V, T_j = 105^{\circ}C$	—	± 30	± 150	μA
		$0 \leq V_{IN} \leq 3.0V, T_j = 130^{\circ}C$	—	± 30	± 200	μA

1. In insensitive to sequence of V_{CC} or V_{CCO} . However, assumes monotonic rise/fall rates for V_{CC} and V_{CCO} , provided $(V_{IN} - V_{CCO}) \leq 3.6V$.

2. $0 < V_{CC} < V_{CC}$ (MAX), $0 < V_{CCO} < V_{CCO}$ (MAX).

3. I_{DK} is additive to I_{PU} , I_{PD} or I_{BH} . Device defaults to pull-up until fuse circuitry is active.

I/O Recommended Operating Conditions

Standard	V_{CCO} (V) ¹	
	Min.	Max.
LV TTL	3.0	3.6
LVC MOS 3.3	3.0	3.6
Extended LVC MOS 3.3 ²	2.7	3.6
LVC MOS 2.5	2.3	2.7
LVC MOS 1.8	1.65	1.95
PCI 3.3	3.0	3.6

1. Typical values for V_{CCO} are the average of the min. and max. values.

2. ispMACH 4000Z only.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,4}$	Input Leakage Current (ispMACH 4000Z)	$0 \leq V_{IN} < V_{CCO}$	—	0.5	1	μA
I_{IH}^1	Input High Leakage Current (ispMACH 4000Z)	$V_{CCO} < V_{IN} \leq 5.5V$	—	—	10	μA
I_{IL}, I_{IH}^1	Input Leakage Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 3.6V, T_j = 105^\circ C$ $0 \leq V_{IN} \leq 3.6V, T_j = 130^\circ C$	—	—	10	μA
$I_{IH}^{1,2}$	Input High Leakage Current (ispMACH 4000V/B/C)	$3.6V < V_{IN} \leq 5.5V, T_j = 105^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V$ $3.6V < V_{IN} \leq 5.5V, T_j = 130^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V$	—	—	20	μA
I_{PU}	I/O Weak Pull-up Resistor Current (ispMACH 4000Z)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-150	μA
I_{PU}	I/O Weak Pull-up Resistor Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-200	μA
I_{PD}	I/O Weak Pull-down Resistor Current	$V_{IL} (\text{MAX}) \leq V_{IN} \leq V_{IH} (\text{MIN})$	30	—	150	μA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (\text{MAX})$	30	—	—	μA
I_{BHHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCO}$	-30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive Current	$0V \leq V_{IN} \leq V_{BHT}$	—	—	150	μA
I_{BHHO}	Bus Hold High Overdrive Current	$V_{BHT} \leq V_{IN} \leq V_{CCO}$	—	—	-150	μA
V_{BHT}	Bus Hold Trip Points	—	$V_{CCO} * 0.35$	—	$V_{CCO} * 0.65$	V
C_1	I/O Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$ $V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (\text{MAX})$	—	8	—	pf
C_2	Clock Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$ $V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (\text{MAX})$	—	6	—	pf
C_3	Global Input Capacitance ³	$V_{CCO} = 3.3V, 2.5V, 1.8V$ $V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (\text{MAX})$	—	6	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tristated. It is not measured with the output driver active. Bus maintenance circuits are disabled.

2. 5V tolerant inputs and I/O should only be placed in banks where $3.0V \leq V_{CCO} \leq 3.6V$.

3. $T_A = 25^\circ C$, $f = 1.0MHz$

4. I_{IH} excursions of up to $1.5\mu A$ maximum per pin above the spec limit may be observed for certain voltage conditions on no more than 10% of the device's I/O pins.

Supply Current, ispMACH 4000V/B/C (Cont.)

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{CC}^4	Standby Power Supply Current	Vcc = 3.3V	—	13	—	mA
		Vcc = 2.5V	—	13	—	mA
		Vcc = 1.8V	—	3	—	mA

- 1. $T_A = 25^\circ\text{C}$, frequency = 1.0 MHz.
- 2. Device configured with 16-bit counters.
- 3. I_{CC} varies with specific device configuration and operating frequency.
- 4. $T_A = 25^\circ\text{C}$

Supply Current, ispMACH 4000Z

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ispMACH 4032ZC						
$ICC^{1, 2, 3, 5}$	Operating Power Supply Current	Vcc = 1.8V, $T_A = 25^\circ\text{C}$	—	50	—	μA
		Vcc = 1.9V, $T_A = 70^\circ\text{C}$	—	58	—	μA
		Vcc = 1.9V, $T_A = 85^\circ\text{C}$	—	60	—	μA
		Vcc = 1.9V, $T_A = 125^\circ\text{C}$	—	70	—	μA
$ICC^{4, 5}$	Standby Power Supply Current	Vcc = 1.8V, $T_A = 25^\circ\text{C}$	—	10	—	μA
		Vcc = 1.9V, $T_A = 70^\circ\text{C}$	—	13	20	μA
		Vcc = 1.9V, $T_A = 85^\circ\text{C}$	—	15	25	μA
		Vcc = 1.9V, $T_A = 125^\circ\text{C}$	—	22	—	μA
ispMACH 4064ZC						
$ICC^{1, 2, 3, 5}$	Operating Power Supply Current	Vcc = 1.8V, $T_A = 25^\circ\text{C}$	—	80	—	μA
		Vcc = 1.9V, $T_A = 70^\circ\text{C}$	—	89	—	μA
		Vcc = 1.9V, $T_A = 85^\circ\text{C}$	—	92	—	μA
		Vcc = 1.9V, $T_A = 125^\circ\text{C}$	—	109	—	μA
$ICC^{4, 5}$	Standby Power Supply Current	Vcc = 1.8V, $T_A = 25^\circ\text{C}$	—	11	—	μA
		Vcc = 1.9V, $T_A = 70^\circ\text{C}$	—	15	25	μA
		Vcc = 1.9V, $T_A = 85^\circ\text{C}$	—	18	35	μA
		Vcc = 1.9V, $T_A = 125^\circ\text{C}$	—	37	—	μA
ispMACH 4128ZC						
$ICC^{1, 2, 3, 5}$	Operating Power Supply Current	Vcc = 1.8V, $T_A = 25^\circ\text{C}$	—	168	—	μA
		Vcc = 1.9V, $T_A = 70^\circ\text{C}$	—	190	—	μA
		Vcc = 1.9V, $T_A = 85^\circ\text{C}$	—	195	—	μA
		Vcc = 1.9V, $T_A = 125^\circ\text{C}$	—	212	—	μA
$ICC^{4, 5}$	Standby Power Supply Current	Vcc = 1.8V, $T_A = 25^\circ\text{C}$	—	12	—	μA
		Vcc = 1.9V, $T_A = 70^\circ\text{C}$	—	16	35	μA
		Vcc = 1.9V, $T_A = 85^\circ\text{C}$	—	19	50	μA
		Vcc = 1.9V, $T_A = 125^\circ\text{C}$	—	42	—	μA

ispMACH 4000V/B/C External Switching Characteristics (Cont.)**Over Recommended Operating Conditions**

Parameter	Description ^{1, 2, 3}	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{PD}	5-PT bypass combinatorial propagation delay	—	5.0	—	7.5	—	10.0	ns
t _{PD_MG}	20-PT combinatorial propagation delay through macrocell	—	5.5	—	8.0	—	10.5	ns
t _S	GLB register setup time before clock	3.0	—	4.5	—	5.5	—	ns
t _{ST}	GLB register setup time before clock with T-type register	3.2	—	4.7	—	5.5	—	ns
t _{SIR}	GLB register setup time before clock, input register path	1.2	—	1.7	—	1.7	—	ns
t _{SIRZ}	GLB register setup time before clock with zero hold	2.2	—	2.7	—	2.7	—	ns
t _H	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t _{HT}	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t _{HIR}	GLB register hold time after clock, input register path	1.0	—	1.0	—	1.0	—	ns
t _{HIRZ}	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t _{CO}	GLB register clock-to-output delay	—	3.4	—	4.5	—	6.0	ns
t _R	External reset pin to output delay	—	6.3	—	9.0	—	10.5	ns
t _{RW}	External reset pulse duration	2.0	—	4.0	—	4.0	—	ns
t _{PTOE/DIS}	Input to output local product term output enable/disable	—	7.0	—	9.0	—	10.5	ns
t _{GPTOE/DIS}	Input to output global product term output enable/disable	—	9.0	—	10.3	—	12.0	ns
t _{GOE/DIS}	Global OE input to output enable/disable	—	5.0	—	7.0	—	8.0	ns
t _{CW}	Global clock width, high or low	2.2	—	2.8	—	4.0	—	ns
t _{GW}	Global gate width low (for low transparent) or high (for high transparent)	2.2	—	2.8	—	4.0	—	ns
t _{WIR}	Input register clock width, high or low	2.2	—	2.8	—	4.0	—	ns
f _{MAX} ⁴	Clock frequency with internal feedback	—	227	—	168	—	125	MHz
f _{MAX} (Ext.)	Clock frequency with external feedback, [1/ (t _S + t _{CO})]	—	156	—	111	—	86	MHz

1. Timing numbers are based on default LVC MOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.3.2

2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.

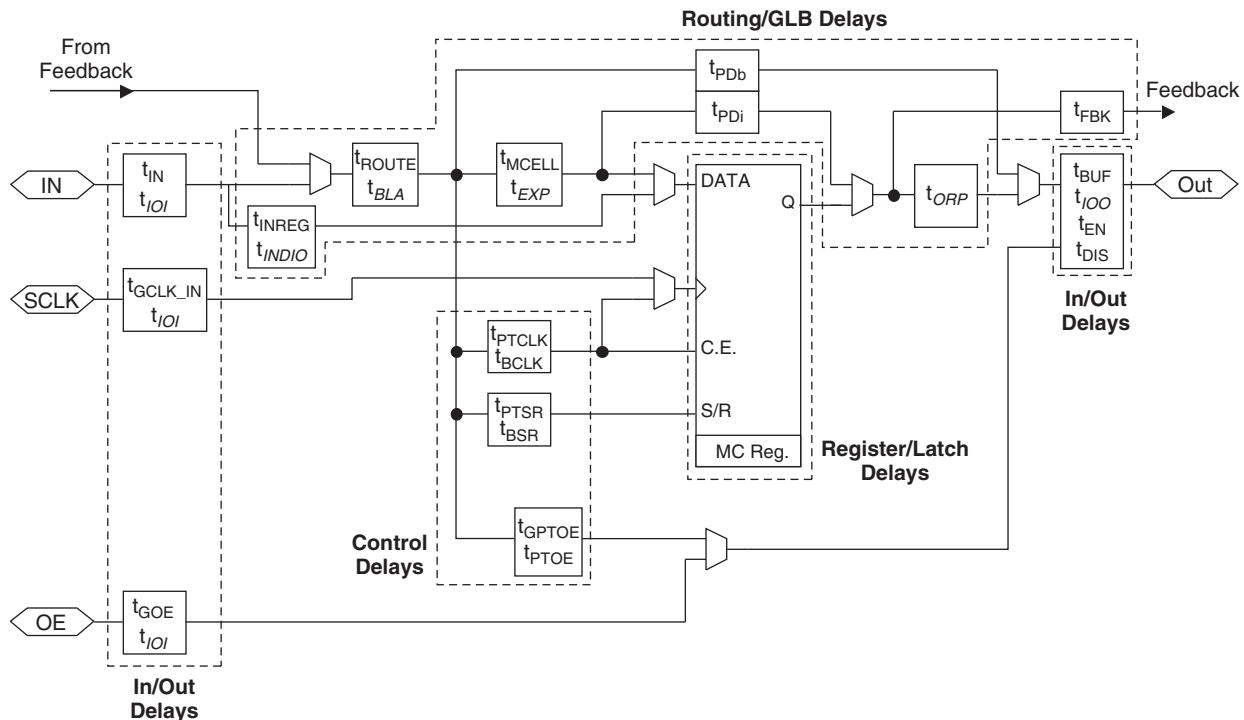
3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

Timing Model

The task of determining the timing through the ispMACH 4000 family, like any CPLD, is relatively simple. The timing model provided in Figure 11 shows the specific delay paths. Once the implementation of a given function is determined either conceptually or from the software report file, the delay path of the function can easily be determined from the timing model. The Lattice design tools report the timing delays based on the same timing model for a particular design. Note that the internal timing parameters are given for reference only, and are not tested. The external timing parameters are tested and guaranteed for every device. For more information on the timing model and usage, refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#).

Figure 11. ispMACH 4000 Timing Model



Note: Italicized items are optional delay adders.

ispMACH 4000V/B/C Internal Timing Parameters (Cont.)**Over Recommended Operating Conditions**

Parameter	Description	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{GPTOE}	Global PT OE Delay	—	5.58	—	5.58	—	5.78	ns
t_{PTOE}	Macrocell PT OE Delay	—	3.58	—	4.28	—	4.28	ns

Timing v.3.2

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the Timing Model in this data sheet for further details.

ispMACH 4000Z Internal Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays								
t_{IN}	Input Buffer Delay	—	0.75	—	0.80	—	0.75	ns
t_{GOE}	Global OE Pin Delay	—	2.25	—	2.25	—	2.30	ns
t_{GCLK_IN}	Global Clock Input Buffer Delay	—	1.60	—	1.60	—	1.95	ns
t_{BUF}	Delay through Output Buffer	—	0.75	—	0.90	—	0.90	ns
t_{EN}	Output Enable Time	—	2.25	—	2.25	—	2.50	ns
t_{DIS}	Output Disable Time	—	1.35	—	1.35	—	2.50	ns
Routing/GLB Delays								
t_{ROUTE}	Delay through GRP	—	1.60	—	1.60	—	2.15	ns
t_{MCELL}	Macrocell Delay	—	0.65	—	0.75	—	0.85	ns
t_{INREG}	Input Buffer to Macrocell Register Delay	—	0.91	—	1.00	—	1.00	ns
t_{FBK}	Internal Feedback Delay	—	0.05	—	0.00	—	0.00	ns
t_{PDb}	5-PT Bypass Propagation Delay	—	0.40	—	0.40	—	0.40	ns
t_{PDi}	Macrocell Propagation Delay	—	0.25	—	0.25	—	0.65	ns
Register/Latch Delays								
t_S	D-Register Setup Time (Global Clock)	0.80	—	0.95	—	0.90	—	ns
t_{S_PT}	D-Register Setup Time (Product Term Clock)	1.35	—	1.95	—	1.90	—	ns
t_{ST}	T-Register Setup Time (Global Clock)	1.00	—	1.15	—	1.10	—	ns
t_{ST_PT}	T-Register Setup Time (Product Term Clock)	1.55	—	1.75	—	2.10	—	ns
t_H	D-Register Hold Time	1.40	—	1.55	—	1.80	—	ns
t_{HT}	T-Register Hold Time	1.40	—	1.55	—	1.80	—	ns
t_{SIR}	D-Input Register Setup Time (Global Clock)	0.94	—	0.90	—	1.50	—	ns
t_{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
t_{HIR}	D-Input Register Hold Time (Global Clock)	1.06	—	1.20	—	1.10	—	ns
t_{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	0.88	—	1.00	—	1.00	—	ns
t_{COi}	Register Clock to Output/Feedback MUX Time	—	0.65	—	0.70	—	0.65	ns
t_{CES}	Clock Enable Setup Time	1.00	—	2.00	—	2.00	—	ns
t_{CEH}	Clock Enable Hold Time	0.00	—	0.00	—	0.00	—	ns
t_{SL}	Latch Setup Time (Global Clock)	0.80	—	0.95	—	0.90	—	ns
t_{SL_PT}	Latch Setup Time (Product Term Clock)	1.55	—	1.95	—	1.90	—	ns
t_{HL}	Latch Hold Time	1.40	—	1.80	—	1.80	—	ns
t_{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.40	—	0.33	—	0.33	ns
t_{PDLi}	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	0.30	—	0.25	—	0.25	ns
t_{SRi}	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.28	—	0.28	—	1.27	ns
t_{SRR}	Asynchronous Reset or Set Recovery Delay	—	2.00	—	1.67	—	1.80	ns
Control Delays								
t_{BCLK}	GLB PT Clock Delay	—	1.30	—	1.50	—	1.55	ns
t_{PTCLK}	Macrocell PT Clock Delay	—	1.50	—	1.70	—	1.55	ns
t_{BSR}	GLB PT Set/Reset Delay	—	1.10	—	1.83	—	1.83	ns
t_{PTSR}	Macrocell PT Set/Reset Delay	—	1.22	—	2.02	—	1.83	ns

ispMACH 4000V/B/C/Z Power Supply and NC Connections¹

Signal	44-pin TQFP ²	48-pin TQFP ²	56-ball csBGA ³	100-pin TQFP ²	128-pin TQFP ²
VCC	11, 33	12, 36	K2, A9	25, 40, 75, 90	32, 51, 96, 115
VCCO0 VCCO (Bank 0)	6	6	F3	13, 33, 95	3, 17, 30, 41, 122
VCCO1 VCCO (Bank 1)	28	30	E8	45, 63, 83	58, 67, 81, 94, 105
GND	12, 34	13, 37	H3, C8	1, 26, 51, 76	1, 33, 65, 97
GND (Bank 0)	5	5	D3	7, 18, 32, 96	10, 24, 40, 113, 123
GND (Bank 1)	27	29	G8	46, 57, 68, 82	49, 59, 74, 88, 104
NC	—	—	4032Z: A8, B10, E1, E3, F8, F10, J1, K3	—	—

1. All grounds must be electrically connected at the board level. However, for the purposes of I/O current loading, grounds are associated with the bank shown.

2. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.

3. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.

**ispMACH 4032V/B/C and 4064V/B/C Logic Signal Connections:
44-Pin TQFP**

Pin Number	Bank Number	ispMACH 4032V/B/C		ispMACH 4064V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	TDI	-	TDI	-
2	0	A5	A^5	A10	A^5
3	0	A6	A^6	A12	A^6
4	0	A7	A^7	A14	A^7
5	0	GND (Bank 0)	-	GND (Bank 0)	-
6	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
7	0	A8	A^8	B0	B^0
8	0	A9	A^9	B2	B^1
9	0	A10	A^10	B4	B^2
10	-	TCK	-	TCK	-
11	-	VCC	-	VCC	-
12	-	GND	-	GND	-
13	0	A12	A^12	B8	B^4
14	0	A13	A^13	B10	B^5
15	0	A14	A^14	B12	B^6
16	0	A15	A^15	B14	B^7
17	1	CLK2/I	-	CLK2/I	-
18	1	B0	B^0	C0	C^0
19	1	B1	B^1	C2	C^1
20	1	B2	B^2	C4	C^2
21	1	B3	B^3	C6	C^3
22	1	B4	B^4	C8	C^4
23	-	TMS	-	TMS	-
24	1	B5	B^5	C10	C^5
25	1	B6	B^6	C12	C^6
26	1	B7	B^7	C14	C^7
27	1	GND (Bank 1)	-	GND (Bank 1)	-
28	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
29	1	B8	B^8	D0	D^0
30	1	B9	B^9	D2	D^1
31	1	B10	B^10	D4	D^2
32	-	TDO	-	TDO	-
33	-	VCC	-	VCC	-
34	-	GND	-	GND	-
35	1	B12	B^12	D8	D^4
36	1	B13	B^13	D10	D^5
37	1	B14	B^14	D12	D^6
38	1	B15/GOE1	B^15	D14/GOE1	D^7
39	0	CLK0/I	-	CLK0/I	-
40	0	A0/GOE0	A^0	A0/GOE0	A^0
41	0	A1	A^1	A2	A^1

ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
19	0	C13	C^10
20	0	C12	C^9
21	0	C10	C^8
22	0	C9	C^7
23	0	C8	C^6
24	0	GND (Bank 0)	-
25	0	C6	C^5
26	0	C5	C^4
27	0	C4	C^3
28	0	C2	C^2
29	0	C0	C^0
30	0	VCCO (Bank 0)	-
31	0	TCK	-
32	0	VCC	-
33	0	GND	-
34	0	D14	D^11
35	0	D13	D^10
36	0	D12	D^9
37	0	D10	D^8
38	0	D9	D^7
39	0	D8	D^6
40	0	GND (Bank 0)	-
41	0	VCCO (Bank 0)	-
42	0	D6	D^5
43	0	D5	D^4
44	0	D4	D^3
45	0	D2	D^2
46	0	D1	D^1
47	0	D0	D^0
48	0	CLK1/I	-
49	1	GND (Bank 1)	-
50	1	CLK2/I	-
51	1	VCC	-
52	1	E0	E^0
53	1	E1	E^1
54	1	E2	E^2
55	1	E4	E^3
56	1	E5	E^4
57	1	E6	E^5
58	1	VCCO (Bank 1)	-
59	1	GND (Bank 1)	-
60	1	E8	E^6
61	1	E9	E^7

ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
105	1	VCCO (Bank 1)	-
106	1	H6	H^5
107	1	H5	H^4
108	1	H4	H^3
109	1	H2	H^2
110	1	H1	H^1
111	1	H0/GOE1	H^0
112	1	CLK3/I	-
113	0	GND (Bank 0)	-
114	0	CLK0/I	-
115	0	VCC	-
116	0	A0/GOE0	A^0
117	0	A1	A^1
118	0	A2	A^2
119	0	A4	A^3
120	0	A5	A^4
121	0	A6	A^5
122	0	VCCO (Bank 0)	-
123	0	GND (Bank 0)	-
124	0	A8	A^6
125	0	A9	A^7
126	0	A10	A^8
127	0	A12	A^9
128	0	A14	A^11

**ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections:
132-Ball csBGA**

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
B1	-	GND	-	GND	-	GND	-
B2	-	TDI	-	TDI	-	TDI	-
C1	0	NC	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
C3	0	NC	-	B0	B^0	C12	C^6
C2	0	A8	A^8	B1	B^1	C10	C^5
D1	0	A9	A^9	B2	B^2	C8	C^4
D3	0	A10	A^10	B4	B^3	C6	C^3
D2	0	A11	A^11	B5	B^4	C4	C^2
E1	0	NC	-	B6	B^5	C2	C^1
E2	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-

**ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections:
132-Ball csBGA (Cont.)**

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
D13	1	D10	D^10	G4	G^3	N6	N^3
D14	1	D9	D^9	G2	G^2	N8	N^4
D12	1	D8	D^8	G1	G^1	N10	N^5
C14	1	I	-	G0	G^0	N12	N^6
C13	1	NC	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
B14	-	TDO	-	TDO	-	TDO	-
A14	-	VCC	-	VCC	-	VCC	-
A13	-	GND	-	GND	-	GND	-
B13	1	NC	-	H14	H^11	O12	O^6
A12	1	I	-	H13	H^10	O10	O^5
C12	1	D7	D^7	H12	H^9	O8	O^4
B12	1	D6	D^6	H10	H^8	O6	O^3
A11	1	D5	D^5	H9	H^7	O4	O^2
C11	1	D4	D^4	H8	H^6	O2	O^1
B11	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
A10	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
B10	1	NC	-	H6	H^5	P12	P^6
C10	1	NC	-	H5	H^4	P10	P^5
B9	1	D3	D^3	H4	H^3	P8	P^4
A9	1	D2	D^2	H2	H^2	P6	P^3
C9	1	D1	D^1	H1	H^1	P4	P^2
A8	1	D0/GOE1	D^0	H0/GOE1	H^0	P2/GOE1	P^1
B8	1	CLK3/I	-	CLK3/I	-	CLK3/I	-
C8	0	CLK0/I	-	CLK0/I	-	CLK0/I	-
B7	-	VCC	-	VCC	-	VCC	-
A7	0	NC ¹	-	NC ¹	-	I ¹	-
C7	0	A0/GOE0	A^0	A0/GOE0	A^0	A2/GOE0	A^1
A6	0	A1	A^1	A1	A^1	A4	A^2
B6	0	A2	A^2	A2	A^2	A6	A^3
C6	0	A3	A^3	A4	A^3	A8	A^4
B5	0	NC	-	A5	A^4	A10	A^5
A5	0	NC	-	A6	A^5	A12	A^6
C5	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
B4	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
A4	0	NC	-	A8	A^6	B2	B^1
C4	0	A4	A^4	A9	A^7	B4	B^2
A3	0	A5	A^5	A10	A^8	B6	B^3
B3	0	A6	A^6	A12	A^9	B8	B^4
A2	0	A7	A^7	A13	A^10	B10	B^5
A1	0	NC	-	A14	A^11	B12	B^6

1. For device migration considerations, these NC pins are input signal pins in ispMACH 4256Z device.

ispMACH 4128V and 4256V Logic Signal Connections: 144-Pin TQFP

Pin Number	Bank Number	ispMACH 4128V		ispMACH 4256V	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	GND	-	GND	-
2	-	TDI	-	TDI	-
3	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
4	0	B0	B^0	C12	C^6
5	0	B1	B^1	C10	C^5
6	0	B2	B^2	C8	C^4
7	0	B4	B^3	C6	C^3
8	0	B5	B^4	C4	C^2
9	0	B6	B^5	C2	C^1
10	0	GND (Bank 0)	-	GND (Bank 0)	-
11	0	B8	B^6	D14	D^7
12	0	B9	B^7	D12	D^6
13	0	B10	B^8	D10	D^5
14	0	B12	B^9	D8	D^4
15	0	B13	B^10	D6	D^3
16	0	B14	B^11	D4	D^2
17	-	NC ²	-	I ²	-
18	0	GND (Bank 0) ¹	-	NC ¹	-
19	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
20	0	NC ²	-	I ²	-
21	0	C14	C^11	E2	E^1
22	0	C13	C^10	E4	E^2
23	0	C12	C^9	E6	E^3
24	0	C10	C^8	E8	E^4
25	0	C9	C^7	E10	E^5
26	0	C8	C^6	E12	E^6
27	0	GND (Bank 0)	-	GND (Bank 0)	-
28	0	C6	C^5	F2	F^1
29	0	C5	C^4	F4	F^2
30	0	C4	C^3	F6	F^3
31	0	C2	C^2	F8	F^4
32	0	C1	C^1	F10	F^5
33	0	C0	C^0	F12	F^6
34	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
35	-	TCK	-	TCK	-
36	-	VCC	-	VCC	-
37	-	GND	-	GND	-
38	0	NC ²	-	I ²	-
39	0	D14	D^11	G12	G^6
40	0	D13	D^10	G10	G^5
41	0	D12	D^9	G8	G^4
42	0	D10	D^8	G6	G^3

ispMACH 4000B (2.5V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4256B	LC4256B-3FT256AC	256	2.5	3	ftBGA	256	128	C
	LC4256B-5FT256AC	256	2.5	5	ftBGA	256	128	C
	LC4256B-75FT256AC	256	2.5	7.5	ftBGA	256	128	C
	LC4256B-3FT256BC	256	2.5	3	ftBGA	256	160	C
	LC4256B-5FT256BC	256	2.5	5	ftBGA	256	160	C
	LC4256B-75FT256BC	256	2.5	7.5	ftBGA	256	160	C
	LC4256B-3F256AC ¹	256	2.5	3	fpBGA	256	128	C
	LC4256B-5F256AC ¹	256	2.5	5	fpBGA	256	128	C
	LC4256B-75F256AC ¹	256	2.5	7.5	fpBGA	256	128	C
	LC4256B-3F256BC ¹	256	2.5	3	fpBGA	256	160	C
	LC4256B-5F256BC ¹	256	2.5	5	fpBGA	256	160	C
	LC4256B-75F256BC ¹	256	2.5	7.5	fpBGA	256	160	C
	LC4256B-3T176C	256	2.5	3	TQFP	176	128	C
	LC4256B-5T176C	256	2.5	5	TQFP	176	128	C
	LC4256B-75T176C	256	2.5	7.5	TQFP	176	128	C
LC4384B	LC4384B-35FT256C	384	2.5	3.5	ftBGA	256	192	C
	LC4384B-5FT256C	384	2.5	5	ftBGA	256	192	C
	LC4384B-75FT256C	384	2.5	7.5	ftBGA	256	192	C
	LC4384B-35F256C ¹	384	2.5	3.5	fpBGA	256	192	C
	LC4384B-5F256C ¹	384	2.5	5	fpBGA	256	192	C
	LC4384B-75F256C ¹	384	2.5	7.5	fpBGA	256	192	C
	LC4384B-35T176C	384	2.5	3.5	TQFP	176	128	C
	LC4384B-5T176C	384	2.5	5	TQFP	176	128	C
LC4512B	LC4512B-35FT256C	512	2.5	3.5	ftBGA	256	208	C
	LC4512B-5FT256C	512	2.5	5	ftBGA	256	208	C
	LC4512B-75FT256C	512	2.5	7.5	ftBGA	256	208	C
	LC4512B-35F256C ¹	512	2.5	3.5	fpBGA	256	208	C
	LC4512B-5F256C ¹	512	2.5	5	fpBGA	256	208	C
	LC4512B-75F256C ¹	512	2.5	7.5	fpBGA	256	208	C
	LC4512B-35T176C	512	2.5	3.5	TQFP	176	128	C
	LC4512B-5T176C	512	2.5	5	TQFP	176	128	C
	LC4512B-75T176C	512	2.5	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4128V	LC4128V-27T144C	128	3.3	2.7	TQFP	144	96	C
	LC4128V-5T144C	128	3.3	5	TQFP	144	96	C
	LC4128V-75T144C	128	3.3	7.5	TQFP	144	96	C
	LC4128V-27T128C	128	3.3	2.7	TQFP	128	92	C
	LC4128V-5T128C	128	3.3	5	TQFP	128	92	C
	LC4128V-75T128C	128	3.3	7.5	TQFP	128	92	C
	LC4128V-27T100C	128	3.3	2.7	TQFP	100	64	C
	LC4128V-5T100C	128	3.3	5	TQFP	100	64	C
	LC4128V-75T100C	128	3.3	7.5	TQFP	100	64	C
LC4256V	LC4256V-3FT256AC	256	3.3	3	ftBGA	256	128	C
	LC4256V-5FT256AC	256	3.3	5	ftBGA	256	128	C
	LC4256V-75FT256AC	256	3.3	7.5	ftBGA	256	128	C
	LC4256V-3FT256BC	256	3.3	3	ftBGA	256	160	C
	LC4256V-5FT256BC	256	3.3	5	ftBGA	256	160	C
	LC4256V-75FT256BC	256	3.3	7.5	ftBGA	256	160	C
	LC4256V-3F256AC ¹	256	3.3	3	fpBGA	256	128	C
	LC4256V-5F256AC ¹	256	3.3	5	fpBGA	256	128	C
	LC4256V-75F256AC ¹	256	3.3	7.5	fpBGA	256	128	C
	LC4256V-3F256BC ¹	256	3.3	3	fpBGA	256	160	C
	LC4256V-5F256BC ¹	256	3.3	5	fpBGA	256	160	C
	LC4256V-75F256BC ¹	256	3.3	7.5	fpBGA	256	160	C
	LC4256V-3T176C	256	3.3	3	TQFP	176	128	C
	LC4256V-5T176C	256	3.3	5	TQFP	176	128	C
	LC4256V-75T176C	256	3.3	7.5	TQFP	176	128	C
	LC4256V-3T144C	256	3.3	3	TQFP	144	96	C
	LC4256V-5T144C	256	3.3	5	TQFP	144	96	C
	LC4256V-75T144C	256	3.3	7.5	TQFP	144	96	C
	LC4256V-3T100C	256	3.3	3	TQFP	100	64	C
	LC4256V-5T100C	256	3.3	5	TQFP	100	64	C
	LC4256V-75T100C	256	3.3	7.5	TQFP	100	64	C
LC4384V	LC4384V-35FT256C	384	3.3	3.5	ftBGA	256	192	C
	LC4384V-5FT256C	384	3.3	5	ftBGA	256	192	C
	LC4384V-75FT256C	384	3.3	7.5	ftBGA	256	192	C
	LC4384V-35F256C ¹	384	3.3	3.5	fpBGA	256	192	C
	LC4384V-5F256C ¹	384	3.3	5	fpBGA	256	192	C
	LC4384V-75F256C ¹	384	3.3	7.5	fpBGA	256	192	C
	LC4384V-35T176C	384	3.3	3.5	TQFP	176	128	C
	LC4384V-5T176C	384	3.3	5	TQFP	176	128	C
	LC4384V-75T176C	384	3.3	7.5	TQFP	176	128	C

ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4512V	LC4512V-35FT256C	512	3.3	3.5	ftBGA	256	208	C
	LC4512V-5FT256C	512	3.3	5	ftBGA	256	208	C
	LC4512V-75FT256C	512	3.3	7.5	ftBGA	256	208	C
	LC4512V-35F256C ¹	512	3.3	3.5	fpBGA	256	208	C
	LC4512V-5F256C ¹	512	3.3	5	fpBGA	256	208	C
	LC4512V-75F256C ¹	512	3.3	7.5	fpBGA	256	208	C
	LC4512V-35T176C	512	3.3	3.5	TQFP	176	128	C
	LC4512V-5T176C	512	3.3	5	TQFP	176	128	C
	LC4512V-75T176C	512	3.3	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-5T48I	32	3.3	5	TQFP	48	32	I
	LC4032V-75T48I	32	3.3	7.5	TQFP	48	32	I
	LC4032V-10T48I	32	3.3	10	TQFP	48	32	I
	LC4032V-5T44I	32	3.3	5	TQFP	44	30	I
	LC4032V-75T44I	32	3.3	7.5	TQFP	44	30	I
	LC4032V-10T44I	32	3.3	10	TQFP	44	30	I
LC4064V	LC4064V-5T100I	64	3.3	5	TQFP	100	64	I
	LC4064V-75T100I	64	3.3	7.5	TQFP	100	64	I
	LC4064V-10T100I	64	3.3	10	TQFP	100	64	I
	LC4064V-5T48I	64	3.3	5	TQFP	48	32	I
	LC4064V-75T48I	64	3.3	7.5	TQFP	48	32	I
	LC4064V-10T48I	64	3.3	10	TQFP	48	32	I
	LC4064V-5T44I	64	3.3	5	TQFP	44	30	I
	LC4064V-75T44I	64	3.3	7.5	TQFP	44	30	I
	LC4064V-10T44I	64	3.3	10	TQFP	44	30	I
LC4128V	LC4128V-5T144I	128	3.3	5	TQFP	144	96	I
	LC4128V-75T144I	128	3.3	7.5	TQFP	144	96	I
	LC4128V-10T144I	128	3.3	10	TQFP	144	96	I
	LC4128V-5T128I	128	3.3	5	TQFP	128	92	I
	LC4128V-75T128I	128	3.3	7.5	TQFP	128	92	I
	LC4128V-10T128I	128	3.3	10	TQFP	128	92	I
	LC4128V-5T100I	128	3.3	5	TQFP	100	64	I
	LC4128V-75T100I	128	3.3	7.5	TQFP	100	64	I
	LC4128V-10T100I	128	3.3	10	TQFP	100	64	I

Lead-Free Packaging**ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Commercial Devices**

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-35MN56C	32	1.8	3.5	Lead-free csBGA	56	32	C
	LC4032ZC-5MN56C	32	1.8	5	Lead-free csBGA	56	32	C
	LC4032ZC-75MN56C	32	1.8	7.5	Lead-free csBGA	56	32	C
	LC4032ZC-35TN48C	32	1.8	3.5	Lead-free TQFP	48	32	C
	LC4032ZC-5TN48C	32	1.8	5	Lead-free TQFP	48	32	C
	LC4032ZC-75TN48C	32	1.8	7.5	Lead-free TQFP	48	32	C
LC4064ZC	LC4064ZC-37MN132C	64	1.8	3.7	Lead-free csBGA	132	64	C
	LC4064ZC-5MN132C	64	1.8	5	Lead-free csBGA	132	64	C
	LC4064ZC-75MN132C	64	1.8	7.5	Lead-free csBGA	132	64	C
	LC4064ZC-37TN100C	64	1.8	3.7	Lead-free TQFP	100	64	C
	LC4064ZC-5TN100C	64	1.8	5	Lead-free TQFP	100	64	C
	LC4064ZC-75TN100C	64	1.8	7.5	Lead-free TQFP	100	64	C
	LC4064ZC-37MN56C	64	1.8	3.7	Lead-free csBGA	56	32	C
	LC4064ZC-5MN56C	64	1.8	5	Lead-free csBGA	56	32	C
	LC4064ZC-75MN56C	64	1.8	7.5	Lead-free csBGA	56	32	C
	LC4064ZC-37TN48C	64	1.8	3.7	Lead-free TQFP	48	32	C
	LC4064ZC-5TN48C	64	1.8	5	Lead-free TQFP	48	32	C
	LC4064ZC-75TN48C	64	1.8	7.5	Lead-free TQFP	48	32	C
LC4128ZC	LC4128ZC-42MN132C	128	1.8	4.2	Lead-free csBGA	132	96	C
	LC4128ZC-75MN132C	128	1.8	7.5	Lead-free csBGA	132	96	C
	LC4128ZC-42TN100C	128	1.8	4.2	Lead-free TQFP	100	64	C
	LC4128ZC-75TN100C	128	1.8	7.5	Lead-free TQFP	100	64	C
LC4256ZC	LC4256ZC-45TN176C	256	1.8	4.5	Lead-free TQFP	176	128	C
	LC4256ZC-75TN176C	256	1.8	7.5	Lead-free TQFP	176	128	C
	LC4256ZC-45MN132C	256	1.8	4.5	Lead-free csBGA	132	96	C
	LC4256ZC-75MN132C	256	1.8	7.5	Lead-free csBGA	132	96	C
	LC4256ZC-45TN100C	256	1.8	4.5	Lead-free TQFP	100	64	C
	LC4256ZC-75TN100C	256	1.8	7.5	Lead-free TQFP	100	64	C

ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-5MN56I	32	1.8	5	Lead-free csBGA	56	32	I
	LC4032ZC-75MN56I	32	1.8	7.5	Lead-free csBGA	56	32	I
	LC4032ZC-5TN48I	32	1.8	5	Lead-free TQFP	48	32	I
	LC4032ZC-75TN48I	32	1.8	7.5	Lead-free TQFP	48	32	I

ispMACH 4000B (2.5V) Lead-Free Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032B	LC4032B-25TN48C	32	2.5	2.5	Lead-Free TQFP	48	32	C
	LC4032B-5TN48C	32	2.5	5	Lead-Free TQFP	48	32	C
	LC4032B-75TN48C	32	2.5	7.5	Lead-Free TQFP	48	32	C
	LC4032B-25TN44C	32	2.5	2.5	Lead-Free TQFP	44	30	C
	LC4032B-5TN44C	32	2.5	5	Lead-Free TQFP	44	30	C
	LC4032B-75TN44C	32	2.5	7.5	Lead-Free TQFP	44	30	C
LC4064B	LC4064B-25TN100C	64	2.5	2.5	Lead-Free TQFP	100	64	C
	LC4064B-5TN100C	64	2.5	5	Lead-Free TQFP	100	64	C
	LC4064B-75TN100C	64	2.5	7.5	Lead-Free TQFP	100	64	C
	LC4064B-25TN48C	64	2.5	2.5	Lead-Free TQFP	48	32	C
	LC4064B-5TN48C	64	2.5	5	Lead-Free TQFP	48	32	C
	LC4064B-75TN48C	64	2.5	7.5	Lead-Free TQFP	48	32	C
	LC4064B-25TN44C	64	2.5	2.5	Lead-Free TQFP	44	30	C
	LC4064B-5TN44C	64	2.5	5	Lead-Free TQFP	44	30	C
	LC4064B-75TN44C	64	2.5	7.5	Lead-Free TQFP	44	30	C
LC4128B	LC4128B-27TN128C	128	2.5	2.7	Lead-Free TQFP	128	92	C
	LC4128B-5TN128C	128	2.5	5	Lead-Free TQFP	128	92	C
	LC4128B-75TN128C	128	2.5	7.5	Lead-Free TQFP	128	92	C
	LC4128B-27TN100C	128	2.5	2.7	Lead-Free TQFP	100	92	C
	LC4128B-5TN100C	128	2.5	5	Lead-Free TQFP	100	92	C
	LC4128B-75TN100C	128	2.5	7.5	Lead-Free TQFP	100	92	C
LC4256B	LC4256B-3FTN256AC	256	2.5	3	Lead-Free ftBGA	256	128	C
	LC4256B-5FTN256AC	256	2.5	5	Lead-Free ftBGA	256	128	C
	LC4256B-75FTN256AC	256	2.5	7.5	Lead-Free ftBGA	256	128	C
	LC4256B-3FTN256BC	256	2.5	3	Lead-Free ftBGA	256	160	C
	LC4256B-5FTN256BC	256	2.5	5	Lead-Free ftBGA	256	160	C
	LC4256B-75FTN256BC	256	2.5	7.5	Lead-Free ftBGA	256	160	C
	LC4256B-3FN256AC ¹	256	2.5	3	Lead-Free fpBGA	256	128	C
	LC4256B-5FN256AC ¹	256	2.5	5	Lead-Free fpBGA	256	128	C
	LC4256B-75FN256AC ¹	256	2.5	7.5	Lead-Free fpBGA	256	128	C
	LC4256B-3FN256BC ¹	256	2.5	3	Lead-Free fpBGA	256	160	C
	LC4256B-5FN256BC ¹	256	2.5	5	Lead-Free fpBGA	256	160	C
	LC4256B-75FN256BC ¹	256	2.5	7.5	Lead-Free fpBGA	256	160	C
	LC4256B-3TN176C	256	2.5	3	Lead-Free TQFP	176	128	C
	LC4256B-5TN176C	256	2.5	5	Lead-Free TQFP	176	128	C
	LC4256B-75TN176C	256	2.5	7.5	Lead-Free TQFP	176	128	C
	LC4256B-3TN100C	256	2.5	3	Lead-Free TQFP	100	64	C
	LC4256B-5TN100C	256	2.5	5	Lead-Free TQFP	100	64	C
	LC4256B-75TN100C	256	2.5	7.5	Lead-Free TQFP	100	64	C

ispMACH 4000V (3.3V) Lead-Free Extended Temperature Devices

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-75TN48E	32	3.3	7.5	Lead-free TQFP	48	32	E
	LC4032V-75TN44E	32	3.3	7.5	Lead-free TQFP	44	30	E
LC4064V	LC4064V-75TN100E	64	3.3	7.5	Lead-free TQFP	100	64	E
	LC4064V-75TN48E	64	3.3	7.5	Lead-free TQFP	48	32	E
	LC4064V-75TN44E	64	3.3	7.5	Lead-free TQFP	44	30	E
LC4128V	LC4128V-75TN144E	128	3.3	7.5	Lead-free TQFP	144	96	E
	LC4128V-75TN128E	128	3.3	7.5	Lead-free TQFP	128	92	E
	LC4128V-75TN100E	128	3.3	7.5	Lead-free TQFP	100	64	E
LC4256V	LC4256V-75TN176E	256	3.3	7.5	Lead-free TQFP	176	128	E
	LC4256V-75TN144E	256	3.3	7.5	Lead-free TQFP	144	96	E
	LC4256V-75TN100E	256	3.3	7.5	Lead-free TQFP	100	64	E

For Further Information

In addition to this data sheet, the following technical notes may be helpful when designing with the ispMACH 4000V/B/C/Z family:

- TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#)
- TN1005, [Power Estimation in ispMACH 4000V/B/C/Z Devices](#)

Revision History

Date	Version	Change Summary
—	—	Previous Lattice releases.
July 2003	17z	Changed device status for LC4064ZC and LC4128ZC to production release and updated/added AC and DC parameters as well as ordering part numbers for LC4064ZC and LC4128ZC devices.
		Improved leakage current specifications for ispMACH 4000Z. For ispMACH 4000V/B/C IIL, IIH condition now includes 0V and 3.6V end points ($0 \leq V_{IN} \leq 3.6V$).
		Added 132-ball chip scale BGA power supply and NC connections.
		Added 132-ball chip scale BGA logic signal connections for LC4064ZC, LC4128ZC and LC4256ZC devices.
		Added lead-free package designators.
October 2003	18z	Hot socketing characteristics footnote 1. has been enhanced; Insensitive to sequence of VCC or VCCO. However, assumes monotonic rise/fall rates for Vcc and Vcco, provided $(V_{IN} - VCCO) \leq 3.6V$.
		Improved LC4064ZC t_S to 2.5ns, t_{ST} to 2.7ns and f_{MAX} (Ext.) to 175MHz, LC4128ZC t_{CO} to 3.5ns and f_{MAX} (Ext.) to 161MHz (version v.2.1).
		Improved associated internal timing numbers and timing adders (version v.2.1).
		Added ispMACH 4000V/B/C/Z ORP Reference Tables.
		Enhanced ORP information in device pinout tables consistent with the ORP Combinations for I/O Blocks tables (table 6, 7, 8 and 9 in page 9-11).
		Corrected GLB/MC/Pad information in the 256-fpBGA pinouts for the LC4256V/B/C 160-I/O version.
		Added the ispMACH 4000 Family Speed Grade Offering table.
		Added the ispMACH 4128ZC Industrial and Automotive Device OPNs
December 2003	19z	Added the ispMACH 4032ZC and 4064ZC Industrial and Automotive Device OPNs